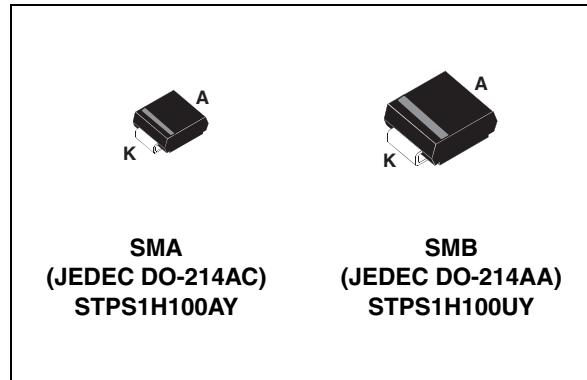


## Automotive high voltage power Schottky rectifier

## Features

- Negligible switching losses
- High junction temperature capability
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- Avalanche capability specified
- ECOPACK®2 compliant component
- AEC-Q101 qualified



## Description

Schottky rectifiers packaged in SMA or SMB, and designed for high frequency miniature switched mode power supplies as DC/DC converters for automotive applications.

**Table 1. Device summary**

Symbol	Value
$I_{F(AV)}$	1 A
$V_{RRM}$	100 V
$T_j$ (max)	175 °C
$V_F$ (max)	0.62 V

# 1 Characteristics

**Table 2. Absolute ratings (limiting values)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		100	V
$I_{F(RMS)}$	Forward rms voltage		10	A
$I_{F(AV)}$	Average forward current		1	A
$I_{FSM}$	Surge non repetitive forward current		50	A
$I_{RRM}$	Repetitive peak reverse current		1	A
$I_{RSM}$	Non repetitive peak reverse current		1	A
$P_{ARM}$	Repetitive peak avalanche power		1500	W
$T_{stg}$	Storage temperature range		- 65 to + 175	°C
$T_j$	Operating junction temperature <sup>(1)</sup>		- 40 to + 175	°C
$dV/dt$	Critical rate of rise of reverse voltage		10000	V/μs

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter	Value	Unit
$R_{th(j-l)}$	Junction to lead	SMA	30
		SMB	25

**Table 4. Static electrical characteristics**

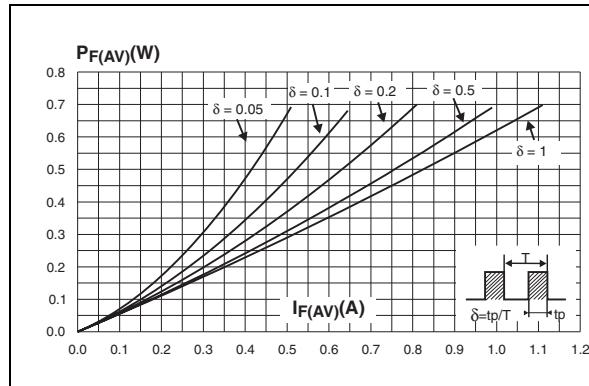
Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			4	μA
		$T_j = 125^\circ\text{C}$			0.2	0.5	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 1 \text{ A}$			0.77	V
		$T_j = 125^\circ\text{C}$			0.58	0.62	
		$T_j = 25^\circ\text{C}$	$I_F = 2 \text{ A}$			0.86	
		$T_j = 125^\circ\text{C}$			0.65	0.7	

1. Pulse test:  $t_p = 5 \text{ ms}$ ,  $\delta < 2\%$
2. Pulse test:  $t_p = 380 \mu\text{s}$ ,  $\delta < 2\%$

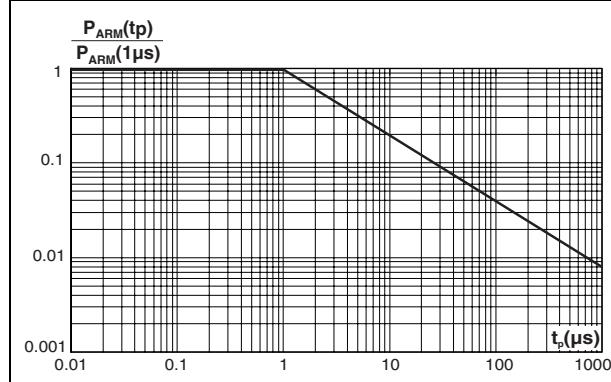
To evaluate the conduction losses use the following equation:

$$P = 0.54 \times I_{F(AV)} + 0.08 I_{F(RMS)}^2$$

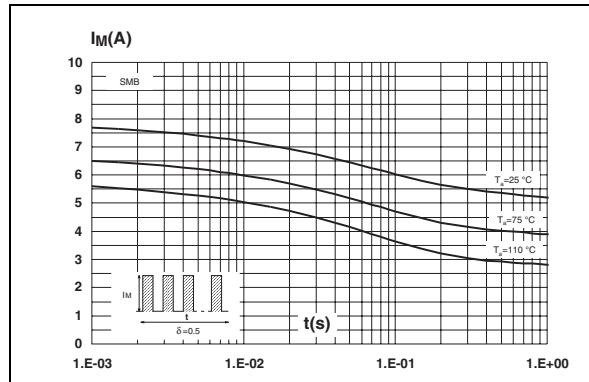
**Figure 1. Average forward power dissipation versus average forward current**



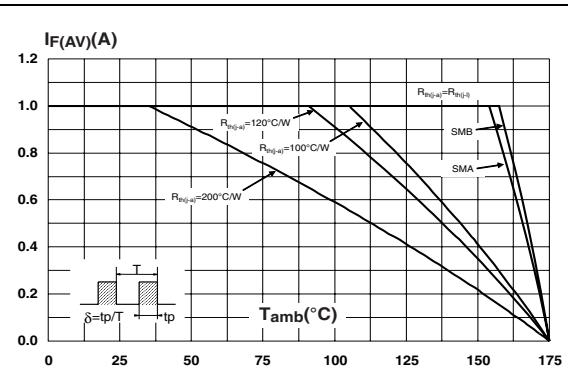
**Figure 3. Normalized avalanche power derating versus pulse duration**



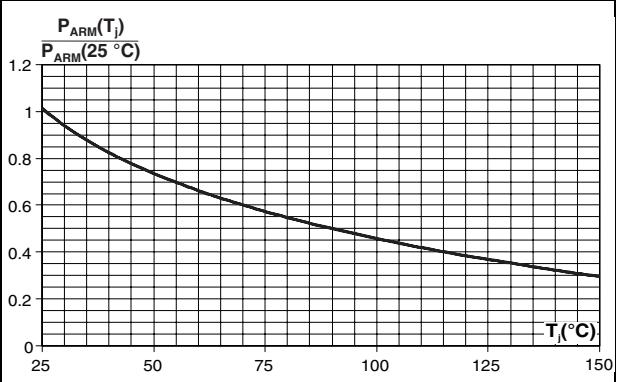
**Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values) (SMB)**



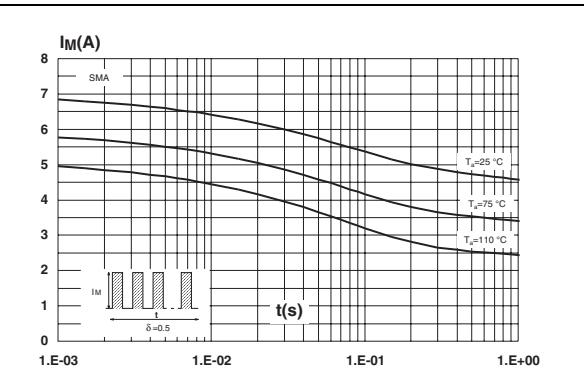
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )**



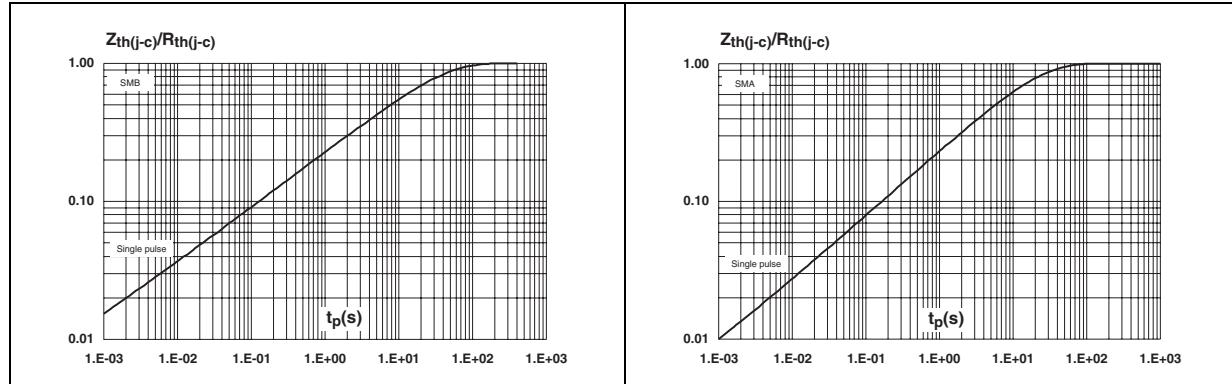
**Figure 4. Normalized avalanche power derating versus junction temperature**



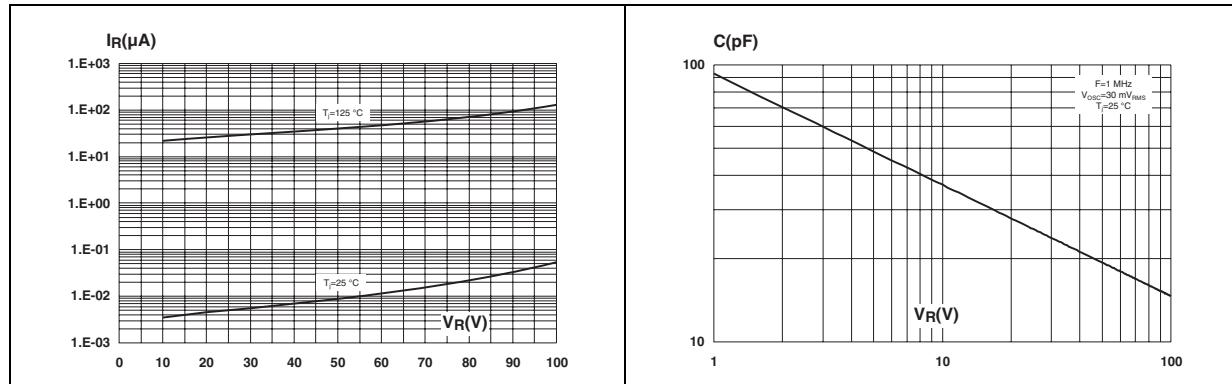
**Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values) (SMA)**



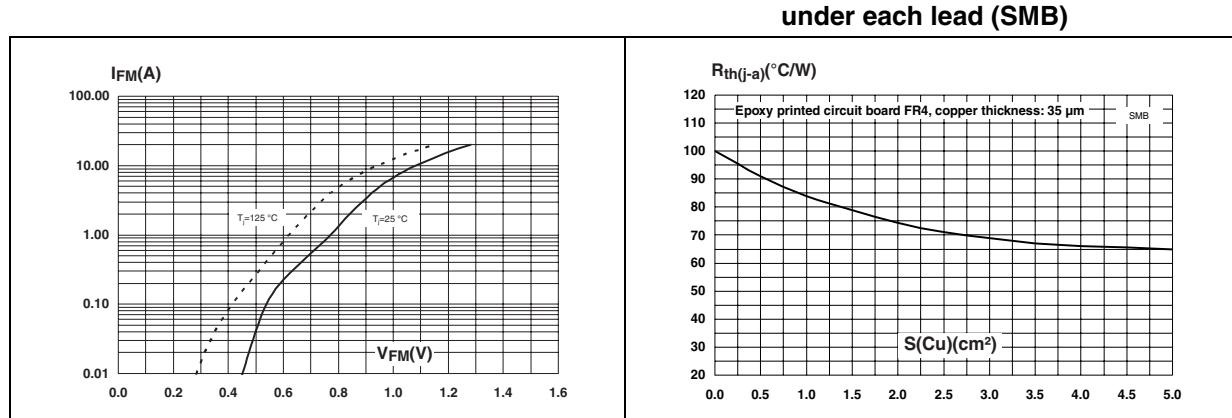
**Figure 7. Relative variation of thermal impedance junction to ambient versus pulse duration (SMB)**



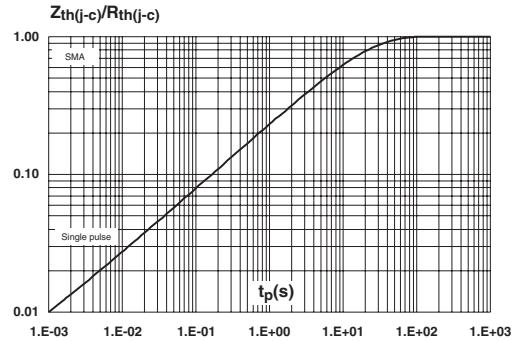
**Figure 9. Reverse leakage current versus reverse voltage applied (typical values)**



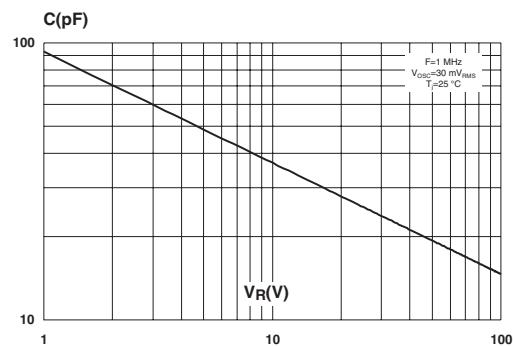
**Figure 11. Forward voltage drop versus forward current (maximum values)**



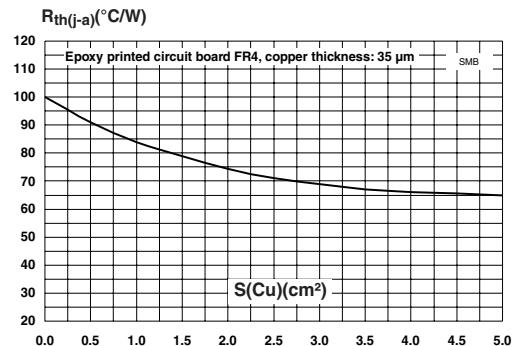
**Figure 8. Relative variation of thermal impedance junction to ambient versus pulse duration (SMA)**

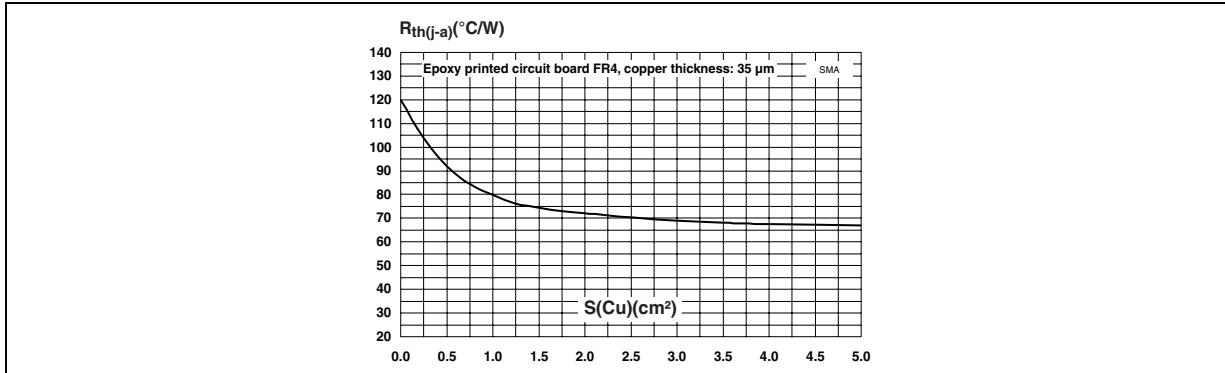


**Figure 10. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 12. Thermal resistance junction to ambient versus copper surface under each lead (SMB)**



**Figure 13. Thermal resistance junction to ambient versus copper surface under each lead (SMA)**

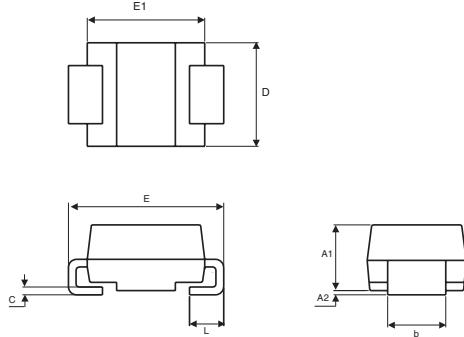
## 2 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
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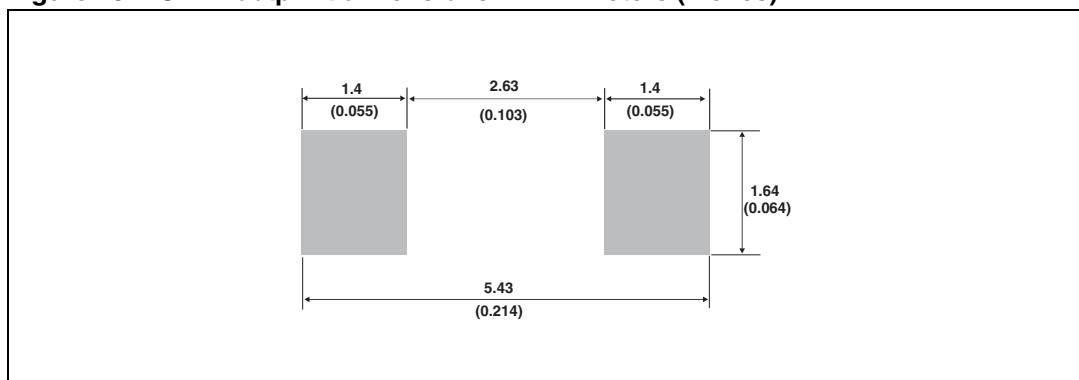
**Figure 14. SMA package dimensions**

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.094
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.006	0.016
D	2.25	2.90	0.089	0.114
E	4.80	5.35	0.189	0.211
E1	3.95	4.60	0.156	0.181
L	0.75	1.50	0.030	0.059



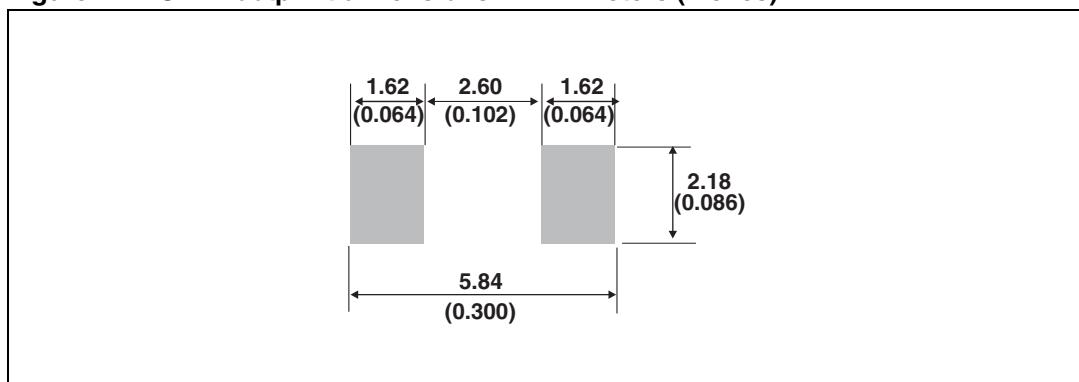
The figure contains three technical drawings of the SMA package. The top drawing shows a top-down view with dimensions E1 (width) and D (height). The middle drawing shows a side view with dimensions E (width), L (length), A1 (top thickness), and A2 (bottom thickness). The bottom drawing shows an end view with dimension b (width).

**Figure 15. SMA footprint dimensions in millimeters (inches)**



**Figure 16.** SMB package dimensions

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
D	3.30	3.95	0.130	0.156
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
L	0.75	1.50	0.030	0.059

**Figure 17.** SMB footprint dimensions in millimeters (inches)

### 3 Ordering information

**Table 5. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS1H100AY	S11Y	SMA	0.068 g	5000	Tape and reel
STPS1H100UY	G11Y	SMB	0.107 g	2500	Tape and reel

### 4 Revision history

**Table 6. Document revision history**

Date	Revision	Changes
03-Dec-2010	1	First issue.

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